



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/829,161

Filed: April 9, 2001

For: METALLIZATION STRUCTURES  
FOR SEMICONDUCTOR DEVICE  
INTERCONNECTS, METHODS FOR  
MAKING SAME, AND  
SEMICONDUCTOR DEVICES  
INCLUDING SAME

Confirmation No.: 8260

Examiner: H. Nguyen

Group Art Unit: 2812

Attorney Docket No.: 3442.1US (96-428.1)

#15/  
w/ Sub Spec (U.S.)  
PATENT

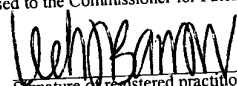
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1-15-03  
L. Spruell

CERTIFICATE OF MAILING

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AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Office Action mailed October 8, 2002, the three-month shortened statutory period for response to which expires on January 8, 2002.